titioner's Docket No. <u>U 013803-1</u>

RECEIPT #1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: CHIEN-PING HUANG

Serial No.: 09/665,818 Filed: September 20, 2000 Group No.: 2814 Examiner: --

For: SEMICONDUCTOR PACKAGE FOR ENHANCING HEAT DISSIPATION

Assistant Commissioner for Patents Washington, D.C. 20231

SECOND REQUEST FOR CORRECTED FILING RECEIP.

1. Attached is a copy of the official filing receipt received from the PTO in the above application for which issuance of a corrected filing receipt is respectfully requested.

2. There is an error with respect to the following data, which is:

[] omitted.

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. 1.8a)

I hereby certify that this correspondence is, on the date shown below, being:

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deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: September 30, 2002

FACSIMILE

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JULIAN H. COHEN

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Correct data Error in 1. Applicant's name 1. [] 2. Applicant's address 2. [] 3. 3. [] Title 4. Filing Date 4. [] 5. 5. [] Serial Number 6. Delete "45688-00006 US-2953-WLJ" Attorney Docket No.: 6. [X] Insert -- U 013803-1 --. 7. Delete "STANLEY R. MOORE ESQ.... 7. [x] Other DALLAS, TEXAS 75202-2799" Insert -- WILLIAM R. EVANS c/o LADAS & PARRY 26 WEST 61ST STREET NEW YORK, N.Y. 10023 --. Reg. No.: (type or print name of practitioner) Tel. No.: () P.O. Address

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APPLICATION NUMBI	ER FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/665,818	09/20/2000	2814	.690	45688- 00006 US- 2953-WLJ	5	20	3

FILING RECEIPT

CC00000005509070

Stanley R Moore Esq Jenkens & Gilchrist PC 3200 Fountain Place 1445 Ross Avenue Dallas, TX 75202-2799

Date Mailed: 10/26/2000

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s) -

Chien-Ping Huang, Hsinchu Hsien, TAIWAN;

Continuing Data as Claimed by Applicant

Foreign Applications

TAIWAN 89115701 08/04/2000

If Required, Foreign Filing License Granted 10/26/2000

NOV 13 2002 CC 2800 MAIL BOOK

Title

Semiconductor package for enhancing heat dissipation

Preliminary Class

257

Data entry by : STEPHANOS, FEKERTE

Team: OIPE

Date: 10/26/2000